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(54) METHOD OF DETECTING ETCHING END POINT

(57) Abstract:

PURPOSE: To provide a method of detecting the etching end point of a film to be etched accurately and stably even in the case that it contains a mask material in a laser spot, concerning the method of detecting the etching end point of a film to be etched.

CONSTITUTION: When forming a mask material, which has an opening, on the film to be etched overlaid on a substrate, and etching the film to be etched with the mask material as an etching mask, it is so constituted as to seek the point of time when the composite waveform changes greatly by applying a laser beam onto the film to be etched inclusive of the mask material, and monitoring the composite waveform where the reflected light intensity of a laser beam and the reflected light intensity of half a cycle ago of a reflected light are added in every unit time.

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